#### 65nm IC technology access, support and IP Blocks

## AIDA 3<sup>rd</sup> Annual Meeting Vienna, 26 March 2014

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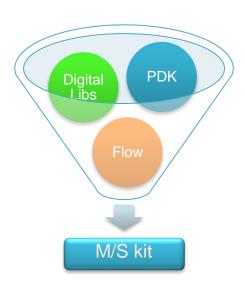
#### Foundry Services News

- Contract with TSMC
  - Foundry access via IMEC
  - Long procedures for negotiating technology information disclosure legal terms and contractual pricing conditions for prototyping and production services
    - Signature of NDA is imminent
  - Contract covers a period of 5 years (2013-2017)



## PDK and Mixed Signal Design kit

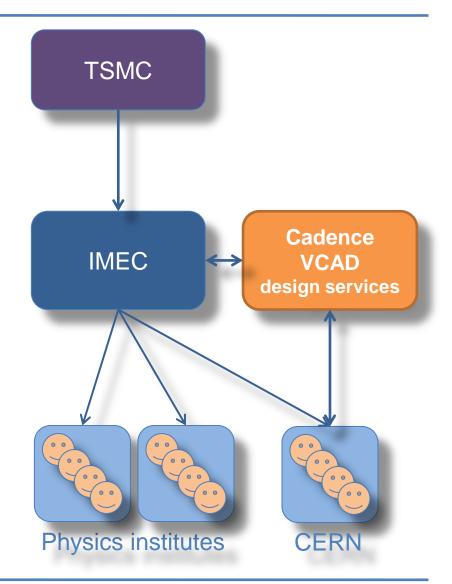
- Development of a "Design Kit" for Mixed Signal environments.
  - With integrated standard cell libraries.
  - Establish well defined Analog & Mixed Signal design workflows.
  - Implemented on modern versions of CAE Tools (Europractice distribution)
  - Physical Layout views available.
  - Suitable for analog, digital and mixed design
- Foundry database not made for full M/S interoperability
  - Technology library and PDK in OA (and CDB)
  - Digital libraries delivered in CDB only
- Integration work done by VCAD (Cadence)
  - Many modifications in the technology file
  - Ported digital libraries to OA for full M/S flow
  - Validated by CERN





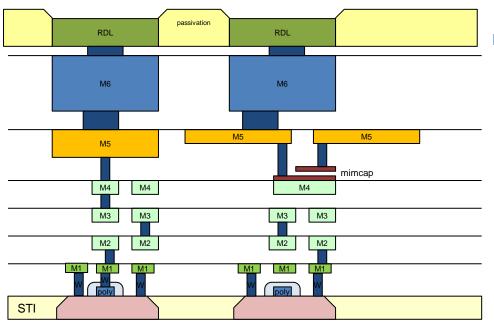
#### TSMC 65nm M/S flow distribution

- M/S flow ready for distribution
  - Waiting for NDA to be signed
- Distribution of package to institutes done by IMEC
  - Sign NDA with institutes
  - Distribute the M/S design kit and workflows
  - Provide maintenance and updates in collaboration with VCAD





#### 65nm supported metal stacks and libraries



- Access to layout views & modification allowed by foundry
  - Clause of no-redistribution except to signatories of NDA (list to be updated annually)
  - Discharge of any foundry liability for modified libraries
  - Modified library is still foundry property
  - Libraries can only be used with TSMC via IMEC

#### CERN 65nm mixed signal (M/S) kit supports

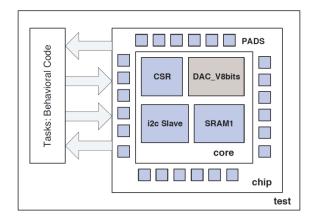
- 2 metal stacks
  - 6+1 metals ("base metal stack")
    - 4-thin, 1-thick, 1-UTM, RDL
  - 9+1 metals (compatible with IMEC mini@sic)
- Optional: (fees apply)
  - 7+1 metals
    - 5-thin, 1-thick, 1-UTM, RDL
- 2 choices of std. cell libraries
  - 9-tracks, standard-Vt
  - 7-tracks, high-Vt
- Standard I/O library
  - Limited radiation performance



## Training: M/S kit Workshops

- A series of Training Workshops for 65nm CMOS will be organized
  - To present the Mixed Signal Kit.
  - To present Analog, Digital and Mixed Signal design Workflows.
  - 1st CERN-internal workshop took place in February 2014
    - 13 participants
  - Cadence (VCAD) design services team:
    - Prepared the training lectures and the accompanying documentation
    - Will provide engineers to lecture in the courses.
  - 3 days training with lectures and hands-on design exercises
  - Workshop modules based on a realistic Mixed Signal Design
  - Training material (scripts, design examples and documentation) made available to participants.
  - All participants must have signed the NDA

Example Mixed Signal ASIC: "8-bit DAC with I<sup>2</sup>C serial interface"





#### Rad-hard IP Blocks in 65nm

- SRAM compiler
- I/O pad library
- Monitoring ADC
- Bandgap
- Rad-hard to 200Mrad according to specifications

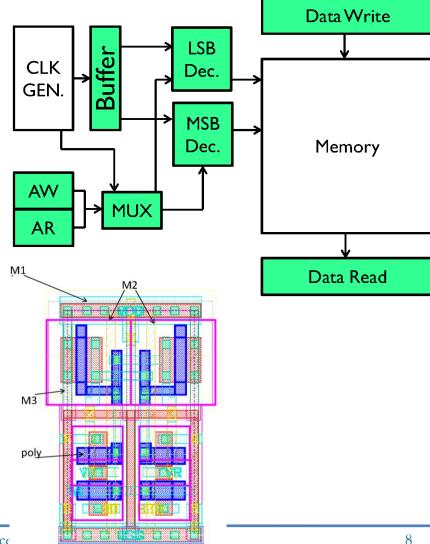


- Pseudo-dual-port (one read + one write in one clock cycle)
- 80 MHz operation
- Minimum size: 128 words of 8 bit
- 1k words of 256 bits Max size:
- Specifications on minimum W of transistors for radiation hardness
  - WPMOS>500nm, WNMOS>200nm
  - Cell size: 1.450 x 2.535 um2
- Part of the blocks are SET tolerant (in green in the figure)
  - If Hamming or other coding is used, SRAM becomes fully SEU tolerant
- Power consumption (simulated for a 1024x32 SRAM)

Read+write: 30 uW/MHz Only read: 16 uW/MHz Only write: 17 uW/MHz

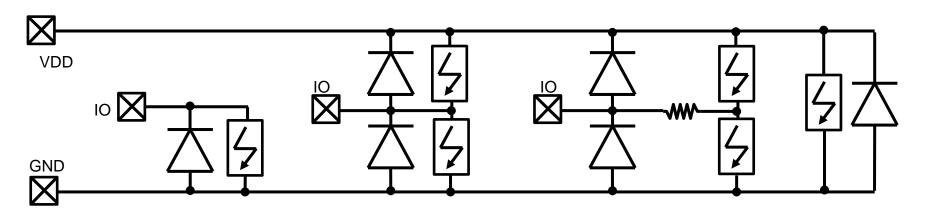
Idle/static: 3 uW

Delivery expected May 2014, radiation tests will follow





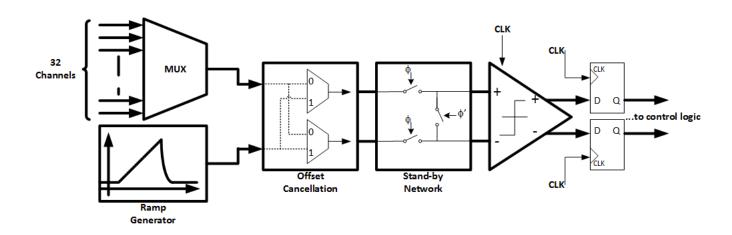
#### ESD structures and I/O pads



- Rated for 1.2V
- Only core devices, thin gate oxide
- Subcontract the development work for rad-hard ESD circuitry
  - Power clamps
  - Low-capacitance analog I/O
  - HBM+CDM ESD-protected I/O for digital
  - Purchase order sent March 2014
- I/O drivers and receivers to be designed at CERN

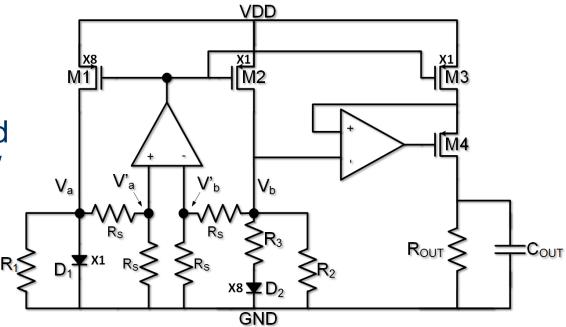
# Monitoring ADC

- ADC
  - 12 bit, 32 channels
  - Sampling rate 5 kS/s
  - 0.8 V full scale
  - power <500uW</p>
  - input max slew rate 1 V/s
- Delivery expected by end 2014,Q2, tests will follow





- Current-mode
- 300mV ± 1% output
  - over p,V,T
  - □ (T from -10 to 50 °C)
- power cons. <240uW</p>
- Delivery expected by end 2014,Q2, tests will follow



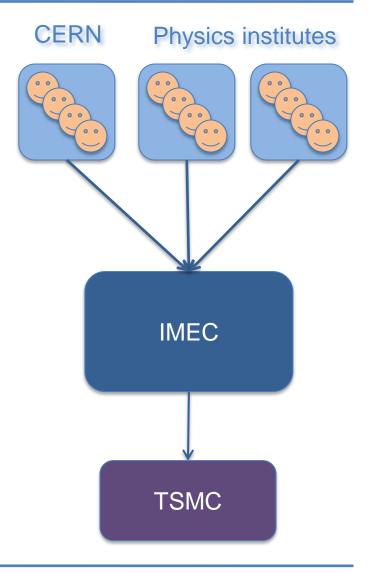


- Foundry provides a wide range of IP blocks
  - Electrical fuse blocks / NVM
  - PLLs
    - 100MHz 1600MHz
    - Jitter enhancement
  - Specialty I/O
    - USB 2.0 / UTMI+
    - DDR2 (up to 800Mpbs), DDR1 (up to 533 Mbps)
    - Crystal oscillator, 32kHz
  - ROM compiler
  - Register File compiler
    - Single- and dual-port
  - SRAM compiler
    - Single-port and dual-port
    - Low-power and low-leakage
- Radiation performance not tested



### Foundry access to TSMC 65nm

- Physics institutes to send the purchase order via CERN
- GDS will be submitted directly to IMEC
- MPW as scheduled from IMEC and foundry
  - Foundry MPW
    - every 4 weeks (for qualified fab)
    - area > 12 mm2
  - mini@sic
    - Twice a year
    - Min. area ~ 4 mm2
    - 7-thin, 1-thick, 1-UTM, RDL
- Additional runs for HEP
  - Metal stack 4-thin, 1-thick, 1-UTM, RDL
  - Possibly every 4 months?
- Engineering/production runs
- CERN will handle logistics (shipping and distribution)



# Soft-IP blocks

- I2C slave
  - 7- and 10-bit addressing
- HDLC communication protocol
  - Variable bit-rate
  - Average 7% bandwidth overhead
- 7b8b communication protocol
  - DC balanced
  - Fixed latency
  - Control characters available

